

Filename: PMP8605 REV_A_bom.xls

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PMP8605 REV_A BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	100uF	Capacitor, multi pattern, SM 805 to 1206	18mm diam.	EKXG401ELL101MMN3S	Nippon Chemi-Con
2	C2	0.22uF	Capacitor, X2, 275V, 20%	17.5mm x 8mm	ECQU2A224ML	Panasonic
	C3	0.22uF	Capacitor, X2, 275V, 20%	17.5mm x 8mm	ECQU2A224ML	Panasonic
1	C4	4700pF	Capacitor, Ceramic, 250V, X7R, 20%	0805	C2012X7R2E472M	TDK
2	C5	470uF	Capacitor, Aluminum Electrolytic, 35V	0.315 inch	35V ZL 470uF 10 X 20	Rubycon
	C6	470uF	Capacitor, Aluminum Electrolytic, 35V	0.315 inch	35V ZL 470uF 10 X 20	Rubycon
5	C7	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
1	C8	47uF	Capacitor, Aluminum Electrolytic, 25V	0.200 * 0.435 inch	Std	Std
1	C9	4700pF	CAP, CERM DISC Y1, 250Vac, 20%	.500 X .310	ECK-ANA472ME	Panasonic
1	C11	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
2	C12	0.047uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H473K	TDK
2	C13	100pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H101K	TDK
1	C14	2200pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
	C15	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
	C16	100pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H101K	TDK
2	C17	1000pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H102K	TDK
	C18	1000pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H102K	TDK
	C19	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
	C20	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
	C21	0.047uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H473K	TDK
1	C22	270pF	Capacitor, Ceramic, 630V, X7R, 10%	0805	C0805C271KBRCTU	Kemet
1	D1	KBP06G	Diode, Bridge Rectifier, 1.5A, 600V	0.580 x 0.145 inch	KBP06G	Diodes
1	D2	MURS160	Diode, Rectifier, 1-A, 600-V	{Size}	MURS160	Diodes Inc
1	D3	MUR840	Diode, Dual Ultrafast, 600V, 8A	TO-220AC	MUR860	On Semi
5	D4	BAS21	Diode, Switching, 200-mA, 200-V, 330-mW	SOT23	BAS21LT1	On Semiconductor
	D5	BAS21	Diode, Switching, 200-mA, 200-V, 330-mW	SOT23	BAS21LT1	On Semiconductor
	D6	BAS21	Diode, Switching, 200-mA, 200-V, 330-mW	SOT23	BAS21LT1	On Semiconductor
	D7	BAS21	Diode, Switching, 200-mA, 200-V, 330-mW	SOT23	BAS21LT1	On Semiconductor
	D8	BAS21	Diode, Switching, 200-mA, 200-V, 330-mW	SOT23	BAS21LT1	On Semiconductor
2	E1					
	E2					
1	F1	2.5A	Fuse, Time Lag, TR5 Series, 2.5A, 250V	0.335	3721250041	Wickmann
1	L1	220uH	Inductor, SMT, 1.6A, 440milliohm	0.51x 0.37 inch	DO3340P-224ML	Coilcraft
1	L2	10mH	Inductor, 0.25A	0.906 x 0.748 inch	RDS 0.7-10	Kaschke
1	L3	2.2 uH	Inductor, Power, 12 milli-Ohm, 6A sat.	0.350 x 0.300 inch	RFB0807-2R2L	Coilcraft
1	L4	48 Ohm @ 100MHz	Inductor, Ferrite Bead, 48 Ohm@100MHz, 10A, 1milliohm	0.484 x 0.484 inch	28F0121-0SR-10	Steward
1	Q1	STP14NM65N	MOSFET, N-ch, 710-V, 12-A, 0.38-Ohms	TO-220V	STP14NM65N	ST
2	Q2	MMBT2907	Bipolar, PNP, 60V, 600mA	SOT23	MMBT2907LT1	On Semiconductor
1	Q3	MMBT3904	Bipolar, NPN, 40-V, 200-mA, 225-W	SOT23	MMBT3904LT1	On Semiconductor
	Q4	MMBT2907	Bipolar, PNP, 60V, 600mA	SOT23	MMBT2907LT1	On Semiconductor

1	R1	10	Resistor, Chip, 1/16W, x%	0805	Std	Std
2	R2	249k	Resistor, Chip, 1/4W, 5%	1210	Std	Std
1	R3	12k	Resistor, Metal -Mite, 25W, ±1%	{Size}	std	Std
	R4	249k	Resistor, Chip, 1/4W, 5%	1210	Std	Std
1	R5	499k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R6	10	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R7	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
	R8	10	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R9	10k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
	R10	10k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R11	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R12	261k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R13	270k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
	R14	78.7k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
	R15	10k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R16	1.62k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R17	9.09k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R18	0.1	Resistor, Chip, 1/4W, 5%	1210	Std	Std
1	R19	301	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R20	49.9k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
	R21	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
	R22	49.9k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R23	20k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
	R24	20k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	RT1	7 Ohms	Thermistor, NTC, 7 Ohms, 4.2-A	0.590 x 0.276	B57237S0709M000	Epcos
1	RT2	10k	Thermistor, NTC	0.095 X 0.150 inch	2322 640 63103	Vishay-BC
1	RT3	275V	Varistor, 275Vac	0.472 x 0.213 inch	SIOV-S10K275E2	Epcos
1	T1	87 uH	Transformer, Flyback ± 10%	33.5mm x 26.5mm	SP-EFS 25/13 / K2006 / 350uH	Kaschke
2	TP1	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100	5000	Keystone
	TP2	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100	5000	Keystone
2	TP3	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
	TP5	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	UCC28600D	IC, Quasi-Resonant Flyback Green Mode Controller	SO8	UCC28600D	Texas Instruments
1	U2	H11A817A	IC, Optocoupler, 5300-V, 80-160% CTR	0.380 x 0.180 inch	H11A817A	Fairchild
1	U3	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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